



Material Composition Sheet

Product: GS9001-CQME3
Package Type: PQFP 44pin (96/tray)
Manufacturer: Gennum Corporation

Date: 11-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Chip		32.19	Al	0.19	0.59	5902
			Si	32.00	99.40	994098
			Sub-total:	32.19	99.99	1000000
Die Attach		5.35	Ag	4.01	74.95	749533
			Epoxy Resin	1.34	25.04	250467
			Sub-total:	5.35	99.99	1000000
Lead Finish External		6.27	Sn	6.27	100.00	1000000
			Sub-total:	6.27	100.00	1000000
Lead Finish Internal Leadframe		120.51	Cu	117.50	97.50	975023
			Fe	2.83	2.34	23484
			P	0.04	0.03	332
			Zn	0.14	0.11	1162
			Sub-total:	120.51	99.98	1000001
Marking Ink		0.01		0.00	0.00	0
			Sub-total:	0.00	0.00	0
Mold Compound		339.41	Epoxy Resin	54.97	16.19	161958
			SiO2	284.44	83.80	838042
			Sub-total:	339.41	99.99	1000000
Wires		0.78	Au	0.78	100.00	1000000
			Sub-total:	0.78	100.00	1000000
Total:		504.52				

GENNUM CORPORATION

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